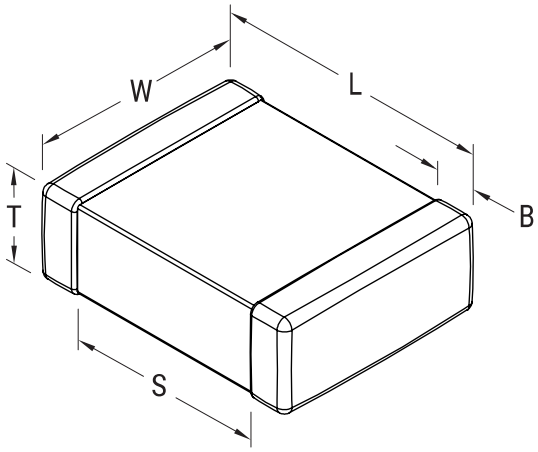
# C1206X102J2TACTU

Aliases (C1206X102J2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 1,000 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm




Click here for the 3D model.

| General Information | |
|---|---|
| Series | SMD Comm X8G HT150C Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 15 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|---|---|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| T | 0.78mm +/-0.20mm |
| S | 1.5mm MIN |
| B | 0.6mm +/-0.25mm |

| Packaging Specifications | |
|---|---|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 4000 |

| Specifications | |
|---|---|
| Capacitance | 1,000 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 200 VDC |
| Dielectric Withstanding Voltage | 500 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |